

Schematic Key for Multilayer and HDI-Technology Build-Ups

| a | b | c | d | e | f | g + h + i |
|---|---|---|---|---|---|-----------|
|---|---|---|---|---|---|-----------|

05 164 FR4 35 L41.35 P10 S1

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

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| Layers | in μ | Material | Build-Up | Assembly |
|-----------------|-----------|----------|----------|----------|
| Layer-1 | 35 μ | Copper | | A1 |
| | 100 μ | Prepreg | | |
| | 100 μ | Prepreg | | |
| Layer-2 | 35 μ | Copper | | A2 |
| | 410 μ | L-FR4 | | |
| | 35 μ | Copper | | |
| Layer-3 | 100 μ | Prepreg | | B |
| | 100 μ | Prepreg | | |
| | 410 μ | L-FR4 | | |
| Layer-4 | 35 μ | Copper | | A1 |
| | 100 μ | Prepreg | | |
| | 100 μ | Prepreg | | |
| Layer-99 | 35 μ | Copper | | A2 |
| | | | | |

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